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TC 1700

Replacement Claims

*Please replace Claim 3 with the following:*

3. The semiconductor manufacturing apparatus according to Claim 1, wherein said vacuum vessel can be divided into a part including said processing chamber and a part having said substrate transport mechanism.

*Please replace Claim 4 with the following:*

4. The semiconductor manufacturing apparatus according to Claim 1, further comprising a plasma generation mechanism for generating plasma in said processing chamber.

*Please replace Claim 5 with the following:*

5. The semiconductor manufacturing apparatus according to Claim 4, wherein said plasma generation mechanism radiates microwave energy through a slot antenna.